



SiHK031N60AE

Gen 5 600 V Superjunction MOSFET in PowerPAK® 10 x 12

LATEST GEN 5 600 V SUPERJUNCTION TECHNOLOGY

- Industry-low $R_{DS(on)}$
- Boosts system efficiency
- Enables higher power ratings and power density
- High I_D current capability

GREAT THERMAL CAPABILITY OF POWERPAK® 10 x 12 FUSE LEAD PACKAGE

- Low profile, dimensions: 9.9 mm x 11.7 mm x 2.3 mm
- TO leadless package
- Integrated Kelvin source connection
- Enables increasing current density

Part Numbers	V_{DS}	$R_{DS(on)_{Typ}}$ (mΩ)	Q_g (nC)	Q_{gd} (nC)
SiHK031N60AE	600	36.8	97	32

APPLICATIONS



AI SERVERS



SOLAR INVERTERS



SERVERS / DATA CENTERS



GAMING PCS



TELECOM



UPS



Fit to 3 kW – 10 kW
Power Supply Solutions



TARGET CIRCUITS – FIT TO LOW FREQUENCY APPLICATIONS

- Slow switch for totem-pole PFC
- Line rectifier, e.g. active bridge PFC
- Inrush current relay circuit

Our Gen 5 600 V Superjunction MOSFET in the PowerPAK® 10 x 12 Package Enables Lower $R_{DS(on)}$ to Boost Efficiency in Power Systems

